

221160US-2 PCT

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
YOSHIYUKI IDO : ATTN: APPLICATION DIVISION
SERIAL NO: 10/088,100 :
FILED: MARCH 22, 2002 :
FOR: INSPECTING DEVICE AND PROBE :
CARD :

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Prior to a first examination on the merits, please amend the above-identified application as follows:

IN THE SPECIFICATION

Please replace the title on page 1, line 1 with the following:

--INSPECTION APPARATUS AND PROBE CARD--.

IN THE CLAIMS

Please amend the claims to read as follows:¹

4. (Amended) The inspecting device according to claim 1,
wherein the ceramic board of said probe card comprises non-oxide ceramic.
5. (Amended) The inspecting device according to claim 1,
wherein said resin thin film comprises thermosetting resin.

¹A marked-up copy of the amendments is attached hereto.

8. (Amended) The probe card according to claim 6,
wherein the resultant conductor circuits formed through said resin layer are interconnected to each other by a via hole.
9. (Amended) The probe card according to claim 6,
wherein said ceramic board comprises non-oxide ceramic.
10. (Amended) The probe card according to claim 6,
wherein said resin layer comprises thermosetting resin.
11. (Amended) The probe card according to claim 6,
wherein said ceramic board is in a disc shape.
12. (Amended) The probe card according to claim 6,
wherein said resin layer is formed so as to cover the whole of at least one of main faces of said ceramic board.

Please add new Claims 13-19 as follows:

13. (New) The inspecting device according to claim 2,
wherein the ceramic board of said probe card comprises non-oxide ceramic.
14. (New) The inspecting device according to claim 3,
wherein the ceramic board of said probe card comprises non-oxide ceramic.
15. (New) The inspecting device according to claim 2,
wherein said resin thin film comprises thermosetting resin.
16. (New) The inspecting device according to claim 3,
wherein said resin thin film comprises thermosetting resin.
17. (New) The inspecting device according to claim 4,
wherein said resin thin film comprises thermosetting resin.

18. (New) The inspecting device according to claim 13,
wherein said resin thin film comprises thermosetting resin.

19. (New) The inspecting device according to claim 14,
wherein said resin thin film comprises thermosetting resin.

REMARKS

Favorable consideration of this application, as presently amended, is respectfully requested.

The present Preliminary Amendment is submitted to place the above-identified application in more proper format under United States practice.

By the present Preliminary Amendment the claims are amended to no longer recite any improper multiple dependencies. Further, subject matter of the cancelled multiple dependencies is set forth in new dependent Claims 13-19.

The present application is believed to be in condition for a full and thorough examination on the merits. An early and favorable consideration of the present application is hereby respectfully requested.

Respectfully submitted,

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Marked-Up Copy Serial No: <u>10/088,100</u> Amendment Filed on: <u>6-26-2002</u>

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IN THE SPECIFICATION

Please replace the title on page 1, with the following:

[INSPECTING DEVICE AND PROBE CARD] INSPECTION APPARATUS AND PROBE CARD

IN THE CLAIMS

Please amend the claims to read as follows:

- 4. (Amended) The inspecting device according to [any of claims] claim 1 [to 3],
wherein the ceramic board of said probe card comprises non-oxide ceramic.
- 5. (Amended) The inspecting device according to [any of claims] claim 1 [to 4],
wherein said resin thin film comprises thermosetting resin.
- 8. (Amended) The probe card according to claim 6 [or 7],
wherein the resultant conductor circuits formed through said resin layer are
interconnected to each other by a via hole.
- 9. (Amended) The probe card according to [any of claims] claim 6 [to 8],
wherein said ceramic board comprises non-oxide ceramic.
- 10. (Amended) The probe card according to [any of claims] claim 6 [to 10],
wherein said resin layer comprises thermosetting resin.
- 11. (Amended) The probe card according to [any of claims] claim 6 [to 10],

wherein said ceramic board is in a disc shape.

12. (Amended) The probe card according to [any of claims] claim 6 [to 11],

wherein said resin layer is formed so as to cover the whole of at least one of main faces of said ceramic board.--